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1. Operating Conditions

PARAMETER	SYMBOL	MIN	MAX	UNIT
Supply voltage	V _{CC}	+1.80	+15	Vdc
Current	Icc		2	mA
R Open	Ro	-	> 30	MOhm
R Closed	R _C	< 100	-	Ohm
Operating ambient temperature	T _{amb}	-20	+70	\mathcal{C}

^{*} Current consumption is determined by the resistance of the application circuit and the supply voltage. The sensor is fully passive, requires no signal conditioning, and operates with currents a low as 0.2 μA.

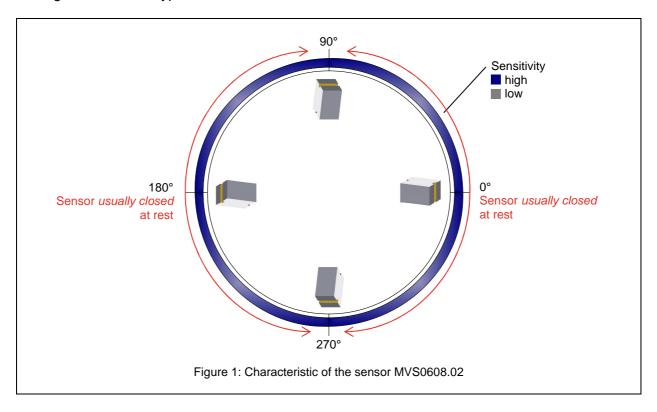
2. Soldering Process

Reflow Soldering Process 260℃, 10 sec

3. Functionality

A mobile, gilded micro sphere is located inside the hollow space of the sensor. When moving, the micro sphere bridges two gilded contacts by switching over from a high resistive to a low resistive state. When the Sensor is at rest, it is **not necessarily closed**. Only in 70% - 99% of time the sensor will be closed when at rest.

The figure shows the typical characteristics of the sensor in excitation and rest.



⁽e.g. max. Icc 0.2µA at Vcc 2V and R 10Meg)

⁽e.g. max. lcc 2.0µA at Vcc 2V and R 1Meg)